■ MN1A7T0200

Туре	MN1A7T0200		
ROM (x8-bit / x16-bit / x32-bit)	Max. 16 M in total		
RAM (x8-bit / x16-bit / x32-bit)	External ROM and RAM		
Package	FLGA152-C-1111 *Lead-free		
Minimum Instruction Execution Time	100 ns (at 2.3 V to 2.7 V, 20 MHz)		
Interrupts	• RESET • IRQ0 to 5 • NMI • Timer 0 to 9 underflow • Timer 8 to 9 compare capture A • Timer 8 to 9 compare capture B • Serial ch.0 to 2 transmission • Serial ch.0 to 2 reception • Serial ch.0 to 2 in communication state • Serial ch.0 to 2 modem status • Serial ch.0 to 2 character • Serial ch.3 to 4 transmission • Serial ch.3 to 4 reception • WDT • A/D conversion finish		
Timer Counter	Timer counter 0: 16-bit × 1 (interval timer, event count, interrupt, A/D conversion trigger) Clock source PS0 underflow; PS1 underflow; external clock Interrupt source		
	Timer counter 1 to 6: 16-bit × 1 (interval timer, event count, timer output, interrupt) Clock source		
	Timer counter 7: 16-bit × 1 (interval timer, event count, timer output, interrupt) Clock source		
	*: timer counter 6 or 7 can be changed in configuration into a 32-bit timer counter.		
	Timer counter 8: 16-bit × 1 (interval timer, event count, output compare, PWM output, one-shot output, input capture, interrupt) Clock source		
	Timer counter 9: 16-bit × 1 (interval timer, event count, output compare, PWM output, one-shot output) Clock source		
	Pre-scaler counters: 2 lines		
Serial Interface	Serial 0, 1, 2 (UART): 5-, 6-, 7-, 8-bit × 3 Clock source baud rate generator; IOCLKH; external clock		
	Serial 3, 4 (SSI): 4- to 16-bit × 2 Clock sourceIOCLKH; external clock		
I/O Pins I/O	40 • Common use		
A/D Inputs	10-bit × 8-ch.		
PWM	16-bit × 2-ch.		
ICR	16-bit × 2-ch.		
OCR	16-bit × 2-ch.		

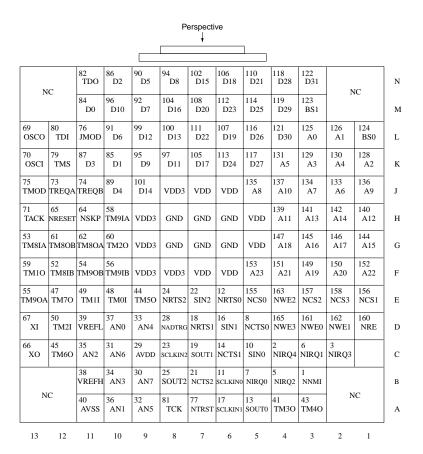
Electrical Characteristics

A/D Characteristic

Parameter	Symbol	Condition	Limit			Unit
			min	typ	max	Unit
Resolution					10	Bits
A/D conversion absolute error		VREFH = 3.0 V VREFL = 0.0 V A/D conversion clock = 6 MHz			± 5	LSB
A/D conversion relative error					± 5	LSB
A/D conversion time			2.0		24	μs

 $(Ta = 25^{\circ}C, AVDD = 3.0 V, AVSS = 0 V)$

Pin Assignment



FLGA152-C-1111 *Lead-free

Support Tool

In-circuit Emulator	Advice (YDC product) (applicable to 16- or 8-bit bus mode), UniSTAC (Sophia Systems Co.,Ltd. product)		
On-board Development Tools	Multi-ICE (ARM product), JEENI (Embedded Performance Inc. product, TOYO Corporation dealings), Logic Analyzer (Agilent Technologies product) NEXTICE for ARM7(Computex Co., Ltd. product)		
ROM Emulator	PARTNER-ETII (KMC product) NEXTICE for ARM7(Computex Co., Ltd. product)		

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